NOTES

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
100 TO 300 MICROINCHES (2.5µm - 7.6µm) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
(40 TO 80 MICROINCHES (1µm - 2µm) THICK).
BODY SURFACE FINISH: VDL 21-24 (1.12-1.6 Rg).

3. PACKAGE MISMatch: BODY OFFSET TO LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220.